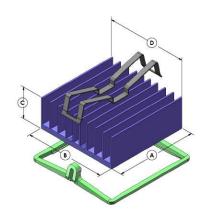
# High Performance BGA Cooling Solutions with superGRIP™ Attachment

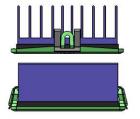


ATS PART # ATS-X53325G-C1-R0

#### **Features & Benefits**

- » Designed for 32.5 x 32.5 mm BGA components
- » superGRIP™ super strong, uniform attachment force helps achieve maximum performance from phase-changing TIM and does not require holes in the PCB
- Allows the heat sink to be detached and reattached without damaging the component and/or the PCB, an important feature in the event a PCB may need to be reworked
- » Meets Telcordia GR-63-Core Office Vibration, ETSI 300 019 Transportation Vibration, and MIL-STD-810 Shock Testing and Unpackaged Drop Testing standards
- » Requires minimal space around the component's perimeter; ideal for densely populated PCBs
- » "Keep-Out" Requirements: An "Un-Populated" boarder zone of 3 mm around the component is necessary to facilitate the Installation/Removal of the superGRIP™. Please refer to the superGRIP™ Keep-Out Guidelines and superGRIP™ Installation/Removal Instructions for further details





## **Thermal Performance**

\*Image above is for illustration purposes only.

AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
200	1.0	5.9	3.2	
300	1.5	4.4		
400	2.0	3.7		
500	2.5	3.3		
600	3.0	3.0		
700	3.5	2.8		
800	4.0	2.6		

## **Product Details**

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
32.5 mm	32.5 mm	12.5 mm	32.5 mm	CHOMERICS T-766	BLUE ANODIZED

#### NOTES:

- DIMENSIONS ARE MEASURED IN MILLIMETERS
- 2) DIMENSIONS A & B REFER TO COMPONENT SIZE
- 3) DIMENSION C = THE HEIGHT OF THE HEAT SINK SHOWN ABOVE AND DOES NOT INCLUDE THE HEIGHT OF THE ATTACHMENT METHOD
- 4) ATS RESERVES THE RIGHT TO UPDATE OR CHANGE IT PRODUCTS WITHOUT
- 5) CONTACT ATS TO LEARN ABOUT CUSTOM OPTIONS AVAILABLE



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).